L Number	Hits	Search Text	DB	Time stamp
1	64234	451/\$.ccls.	USPAT;	2004/08/10 09:47
			US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
	1215		IBM_TDB USPAT;	2004/08/10 09:47
2	1315	pressure adj sensitive adj paper	US-PGPUB;	2004/08/10 09:47
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	1	451/\$.ccls. and (pressure adj sensitive	USPĀT;	2004/08/10 09:46
[adj paper)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
4	32466	451/\$.ccls.	IBM_TDB USOCR	2004/08/10 09:47
4 5	32466	451/5.CC18. pressure adj sensitive adj paper	USOCR	2004/08/10 09:47
6	0	451/\$.ccls. and (pressure adj sensitive	USOCR	2004/08/10 09:47
		adj paper)		=====================================
10	3275840	condition conditioner conditioning	USPAT;	2004/08/10 09:49
		conditions conditioners conditioned	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
	270000	forforg gub-tt zub-tt	IBM_TDB	2004/08/10 09:49
11	2709203	wafer wafers substrate substrates semiconductor semiconductors	USPAT; US-PGPUB;	2004/08/10 09:49
		Semiconductor Semiconductors	EPO; JPO;	
			DERWENT;	
i			IBM TDB	
12	2021902	sensor sensors sensing sense sensed senses	USPAT;	2004/08/10 09:49
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
13	10377	(condition conditioner conditioning	IBM_TDB USPAT;	2004/08/10 10:11
12	10377	conditions conditioners conditioned) same	US-PGPUB;	2004/00/10 10:11
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) same (sensor	DERWENT;	
		sensors sensing sense sensed senses)	IBM_TDB	
14	3212959	pressure pressures	USPAT;	2004/08/10 09:50
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
15	296272	database databases (data adj (base bases))	USPAT;	2004/08/10 09:51
		(4454 44) (4464 44)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0004/00/10 00 70
16	2		USPAT;	2004/08/10 09:53
		conditions conditioners conditioned) same (wafer wafers substrate substrates	US-PGPUB; EPO; JPO;	
		(water waters substrate substrates semiconductor semiconductors) same (sensor	DERWENT;	
		sensors sensing sense sensed senses))	IBM TDB	
		same (pressure pressures) same (database		
		databases (data adj (base bases)))		
17	14	1 ' '	USPAT;	2004/08/10 09:54
		conditions conditioners conditioned) same	US-PGPUB;	
		(wafer wafers substrate substrates semiconductor semiconductors) same (sensor	EPO; JPO; DERWENT;	
		sensors sensing sense sensed senses)) and	IBM TDB	
		((pressure pressures) with (database	-222	
		databases (data adj (base bases))))		
18	247	451/\$.ccls. and ((condition conditioner	USPAT;	2004/08/10 09:58
		conditioning conditions conditioners	US-PGPUB;	
		conditioned) same (wafer wafers substrate	EPO; JPO;	
		substrates semiconductor semiconductors)	DERWENT;	
		same (sensor sensors sensing sense sensed	IBM_TDB	
		senses))	l	<u> </u>

19	63	(451/\$.ccls. and ((condition conditioner	USPAT;	2004/08/10 10:01
		conditioning conditions conditioners conditioned) same (wafer wafers substrate	US-PGPUB; EPO; JPO;	
ļ		substrates semiconductor semiconductors)	DERWENT;	
		same (sensor sensors sensing sense sensed	IBM TDB	
		senses))) and conditioner		
20	0	((451/\$.ccls. and ((condition conditioner	USPAT;	2004/08/10 09:59
ļ ļ		conditioning conditions conditioners	US-PGPUB;	
ļ ļ		conditioned) same (wafer wafers substrate	EPO; JPO;	
-	•	substrates semiconductor semiconductors)	DERWENT;	
		same (sensor sensors sensing sense sensed	IBM_TDB	
		senses))) and conditioner) and (pressure adj sensitive adj paper)		
21	2894295	determine determining determines	USPAT;	2004/08/10 10:02
21	2034233	determined	US-PGPUB;	2001,00,10 10.02
		40002111104	EPO; JPO;	
	į		DERWENT;	
1			IBM_TDB	
22	4118120		USPAT;	2004/08/10 10:03
		senses) or (determine determining	US-PGPUB;	
1		determines determined)	EPO; JPO;	
			DERWENT;	
23	42	(prossure add sensitive add paper) with	IBM_TDB USPAT;	2004/08/10 10:07
23	42	(pressure adj sensitive adj paper) with ((sensor sensors sensing sense sensed	USPAT; US-PGPUB;	2004/00/10 10:0/
		senses or (determine determining	EPO; JPO;	
		determines determined))	DERWENT;	
		4000	IBM TDB	
24	0	"10" with ((sensor sensors sensing sense	USPĀT;	2004/08/10 10:07
		sensed senses) or (determine determining	US-PGPUB;	
		determines determined)) with (pressure adj	EPO; JPO;	
		sensitive adj paper)	DERWENT;	
25	3	/condition conditioner conditioning	IBM_TDB USPAT;	2004/08/10 10:10
25] 3	(condition conditioner conditioning conditions conditioners conditioned) with	US-PGPUB;	2004/00/10 10:10
		((sensor sensors sensing sense sensed	EPO; JPO;	
		senses) or (determine determining	DERWENT;	
		determines determined)) with (pressure adj	IBM TDB	
		sensitive adj paper)	_	
26	3	, , ,	USPAT;	2004/08/10 10:11
		conditions conditioners conditioned) with	US-PGPUB;	
		(pressure adj sensitive adj paper)) same	EPO; JPO;	
		((sensor sensors sensing sense sensed senses) or (determine determining	DERWENT; IBM TDB	
		determines determined))	1011_100	
27	3023		USPAT;	2004/08/10 10:13
		conditions conditioners conditioned) with	US-PGPUB;	
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) with (sensor	DERWENT;	
20		sensors sensing sense sensed senses)	IBM_TDB	2004/00/10 10-13
28	0	((condition conditioner conditioning conditions conditioners conditioned) with	USPAT; US-PGPUB;	2004/08/10 10:13
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) with (sensor	DERWENT;	
		sensors sensing sense sensed senses)) and	IBM TDB	
		(pressure adj sensitive adj paper)	_	
29	167	((condition conditioner conditioning	USPAT;	2004/08/10 10:13
		conditions conditioners conditioned) with	US-PGPUB;	
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) with (sensor sensors sensing sense sensed senses))	DERWENT; IBM TDB	
		sensors sensing sense sensed senses)	100	
30	3	(((condition conditioner conditioning	USPAT;	2004/08/10 10:15
		conditions conditioners conditioned) with	US-PGPUB;	,
		(wafer wafers substrate substrates	EPO; JPO;	
		semiconductor semiconductors) with (sensor	DERWENT;	
		sensors sensing sense sensed senses))	IBM_TDB	
		with conditioner) and 451/\$.ccls.	·	L

31	749	(polishing adj pad) with conditioner	USPAT; US-PGPUB;	2004/08/10 10:15
			EPO; JPO;	
			DERWENT; IBM TDB	
32	0		USPĀT;	2004/08/10 10:15
		((polishing adj pad) with conditioner)	US-PGPUB;	
			EPO; JPO; DERWENT;	
	i		IBM TDB	
33	25	, , , , , , , , , , , , , , , , , , , ,	USPĀT;	2004/08/10 10:16
		conditions conditioners conditioned) with	US-PGPUB;	
		(wafer wafers substrate substrates semiconductor semiconductors) with (sensor	EPO; JPO; DERWENT;	
		sensors sensing sense sensed senses)) and	IBM_TDB	
		((polishing adj pad) with conditioner)		
34	71653	(uniformity uniform) with (pressure	USPAT; US-PGPUB;	2004/08/10 10:17
		pressures)	EPO; JPO;	
			DERWENT;	
25			IBM_TDB	2004/00/10 10 17
35	292	((uniformity uniform) with (pressure pressures)) and ((condition conditioner	USPAT; US-PGPUB;	2004/08/10 10:17
		conditioning conditions conditioners	EPO; JPO;	
		conditioned) same (wafer wafers substrate	DERWENT;	
		substrates semiconductor semiconductors) same (sensor sensors sensing sense sensed	IBM_TDB	
		same (sensor sensors sensing sense sensed senses))		
36	71653	((uniformity uniform) with (pressure	USPAT;	2004/08/10 10:17
		pressures)) samel13	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
37	44	((uniformity uniform) with (pressure	USPAT;	2004/08/10 10:19
		pressures)) same ((condition conditioner conditioning conditions conditioners	US-PGPUB; EPO; JPO;	
		conditioning conditions conditioners conditioned) same (wafer wafers substrate	DERWENT;	
		substrates semiconductor semiconductors)	IBM_TDB	
		same (sensor sensors sensing sense sensed senses))		
38	0	uniformity near3 pressure near3	USPAT;	2004/08/10 10:19
	_	conditioner	US-PGPUB;	
			EPO; JPO;	
		,	DERWENT; IBM TDB	
39	0	uniformity near5 pressure near5	USPĀT;	2004/08/10 10:20
		conditioner	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
40	0	(uniformity adj3 pressure) near5	USPĀT;	2004/08/10 10:20
		conditioner	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
41	1682	(uniformity adj3 pressure)	USPĀT;	2004/08/10 10:20
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/10
43	11	<pre>(((uniformity adj3 pressure)) and conditioner) and polishing</pre>	USPAT; US-PGPUB;	2004/08/10 10:20
		conditioner, and portaining	EPO; JPO;	
			DERWENT;	
42	48	(/uniformity adi2 processes) \ and	IBM_TDB USPAT;	2004/08/10 10:35
42	48	((uniformity adj3 pressure)) and conditioner	USPAT; US-PGPUB;	2004/00/10 10:35
			EPO; JPO;	
			DERWENT;	
	L		IBM_TDB	

44	11	((polishing adj pad) with conditioner)	USPAT;	2004/08/10 10:	58
ļ		with ((uniformity uniform) with (pressure	US-PGPUB;		
ŀ		pressures))	EPO; JPO;		1
			DERWENT;		1
			IBM TDB		
45	4	"6477447"	USPĀT;	2004/08/10 10:	:59
			US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM TDB		